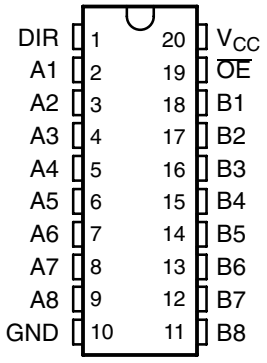
- **Operating Voltage Range of 4.5 V to 5.5 V**
- **State-of-the-Art BiCMOS Design Significantly Reduces I_{CCZ}**
- **B Port Has Equivalent 33-Ω Series Resistors, So No External Resistors Are Required**
- **ESD Protection Exceeds JESD 22**
  - **2000-V Human-Body Model (A114-A)**
  - **200-V Machine Model (A115-A)**
  - **1000-V Charged-Device Model (C101)**

DB, DW, N, OR NS PACKAGE
(TOP VIEW)



description/ordering information

The SN74BCT2245 octal transceiver and line/MOS driver is designed for asynchronous communication between data buses.

The device allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable ($\overline{OE}$) input can disable the devices so that both buses are effectively isolated.

To ensure the high-impedance state during power up or power down, $\overline{OE}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The B-port outputs, which are designed to source or sink up to 12 mA, include 33-Ω series resistors to reduce overshoot and undershoot.

ORDERING INFORMATION

T_A	PACKAGE†		ORDERABLE PART NUMBER	TOP-SIDE MARKING
0°C to 70°C	PDIP – N	Tube	SN74BCT2245N	SN74BCT2245N
	SOIC – DW	Tube	SN74BCT2245DW	BCT2245
		Tape and reel	SN74BCT2245DWR	
	SOP – NS	Tape and reel	SN74BCT2245NSR	BCT2245
	SSOP – DB	Tape and reel	SN74BCT2245DBR	BA245

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OPERATION
$\overline{OE}$	DIR	
L	L	B data to A bus
L	H	A data to B bus
H	X	Isolation

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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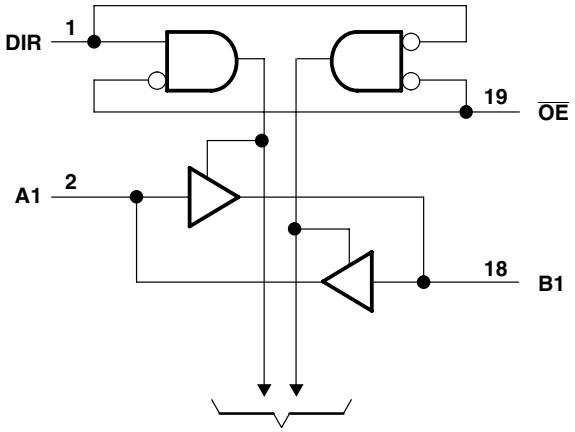
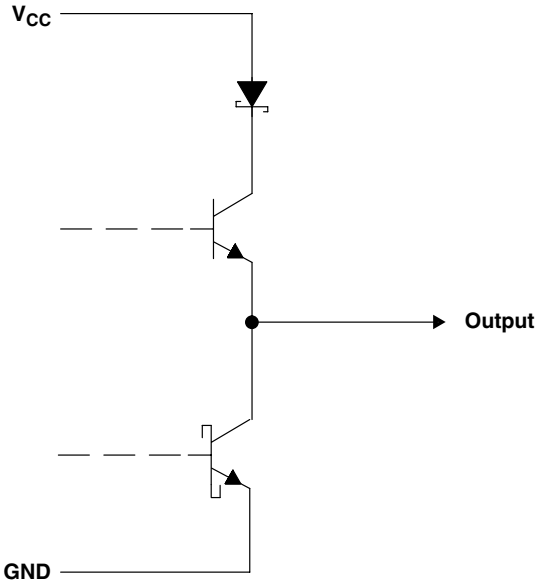
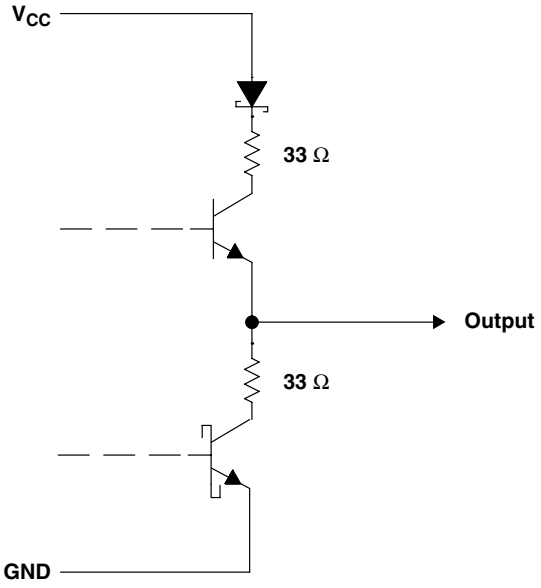
logic diagram (positive logic)



schematic of A-port outputs



schematic of B-port outputs



All resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} . . . . . –0.5 V to 7 V
Input voltage range, V_I (see Note 1) . . . . . –0.5 V to 7 V
Voltage range applied to any output in the disabled or power-off state, V_O . . . . . –0.5 V to 5.5 V
Voltage range applied to any output in the high state, V_O . . . . . –0.5 V to V_{CC}
Input clamp current, I_{IK} . . . . . –30 mA
Current into any output in the low state, I_O . . . . . 60 mA
Package thermal impedance, θ_{JA} (see Note 2): DB package . . . . . 70°C/W
DW package . . . . . 58°C/W
N package . . . . . 69°C/W
NS package . . . . . 60°C/W
Storage temperature range, T_{stg} . . . . . –65°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. The package thermal impedance is calculated in accordance with JESD 51-7.

recommended operating conditions (see Note 3)

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage		4.5	5	5.5	V
V_{IH}	High-level input voltage		2			V
V_{IL}	Low-level input voltage				0.8	V
I_{IK}	Input clamp current				–18	mA
I_{OH}	High-level output current	A port			–3	mA
		B port			–12	
I_{OL}	Low-level output current	A port			24	mA
		B port			12	
T_A	Operating free-air temperature		0		70	°C

NOTE 3: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

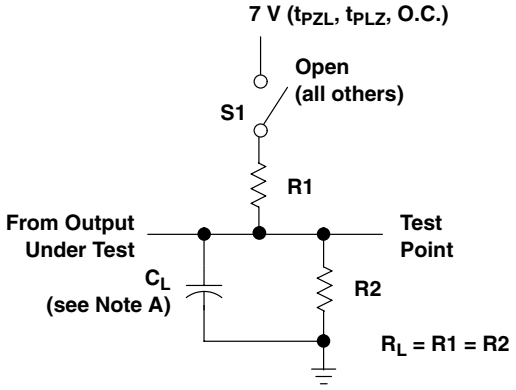
PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IK}		V_{CC} = 4.5 V,	I_I = –18 mA			–1.2	V
V_{OH}	A port	V_{CC} = 4.5 V	I_{OH} = –1 mA	2.5	3.4		V
			I_{OH} = –3 mA	2.4	3.3		
	B port	V_{CC} = 4.5 V	I_{OH} = –1 mA	2.4	3.3		
			I_{OH} = –12 mA	2	3.2		
V_{OL}	A port	V_{CC} = 4.5 V,	I_{OL} = 24 mA		0.35	0.5	V
	B port	V_{CC} = 4.5 V	I_{OL} = 1 mA			0.5	
			I_{OL} = 12 mA			0.8	
I_I		V_{CC} = 5.5 V,	V_I = 5.5 V			0.1	mA
I_{IH}‡	A or B port	V_{CC} = 5.5 V,	V_I = 2.7 V			70	µA
	Control input					20	
I_{IL}‡		V_{CC} = 5.5 V,	V_I = 0.5 V			–0.65	mA
I_{OS}§	A port	V_{CC} = 5.5 V,	V_O = 0	–60		–150	mA
	B port			–100		–225	
I_{CCL}	A to B	V_{CC} = 5.5 V,	Outputs open		63	100	mA
	B to A				40	64	
I_{CCH}	A to B	V_{CC} = 5.5 V,	Outputs open		37	59	mA
	B to A				29	46	
I_{CCZ}	A to B	V_{CC} = 5.5 V,	Outputs open		9	15	mA
	B to A				8	14	
C_i	Control input	V_{CC} = 5 V,	V_I = 2.5 V or 0.5 V		7		pF
C_{io}	A to B	V_{CC} = 5 V,	V_O = 2.5 V or 0.5 V		9		pF
	B to A				12		

† All typical values are at V_{CC} = 5 V, T_A = 25°C.
‡ For I/O ports, the parameters I_{IH} and I_{IL} include the off-state output current.
§ Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

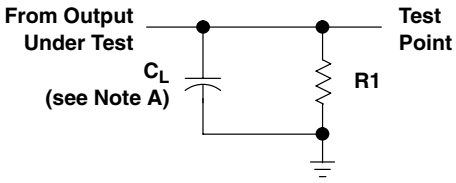
switching characteristics over recommended ranges of supply voltage and operating free-air temperature, C_L = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V_{CC} = 5 V, T_A = 25°C			MIN	MAX	UNIT
			MIN	TYP	MAX			
t_{PLH}	A	B	1	3.3	4.9	1	5.8	ns
	B	A	1.7	4.2	6.1	1.7	7	
t_{PHL}	A	B	2.5	5.1	6.9	2.5	7.8	ns
	B	A	2.2	4.7	7.1	2.2	7.7	
t_{PZH}	$\overline{OE}$	B	3.2	6.2	8.6	3.2	9.9	ns
		A	3.8	7.2	9.5	3.8	11.1	
t_{PZL}	$\overline{OE}$	B	5.6	8.3	10.9	5.6	12.2	ns
		A	4.2	7.6	10.1	4.2	11.4	
t_{PHZ}	$\overline{OE}$	B	2.6	5.2	7.1	2.6	8.2	ns
		A	3.1	5.7	8	3.1	9.4	
t_{PLZ}	$\overline{OE}$	B	3.5	6	7.9	3.5	9.2	ns
		A	2.3	4.7	6.5	2.3	7.6	

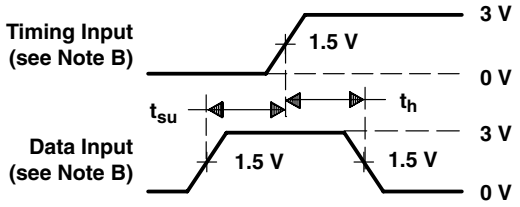
PARAMETER MEASUREMENT INFORMATION



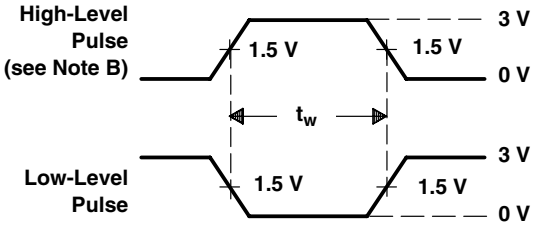
LOAD CIRCUIT FOR
3-STATE AND OPEN-COLLECTOR OUTPUTS



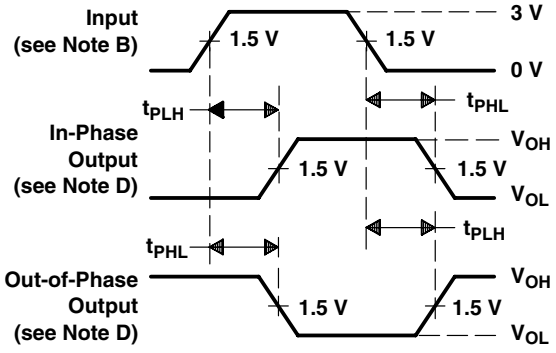
LOAD CIRCUIT FOR
TOTEM-POLE OUTPUTS



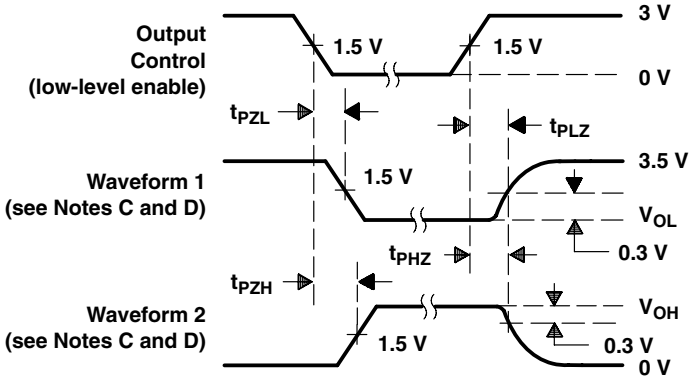
VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES (see Note D)



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES, 3-STATE OUTPUTS

NOTES: A. C_L includes probe and jig capacitance.
B. All input pulses are supplied by generators having the following characteristics: PRR ≤ 10 MHz, $t_r = t_f \leq 2.5$ ns, duty cycle = 50%.
C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
D. The outputs are measured one at a time with one transition per measurement.
E. When measuring propagation delay times of 3-state outputs, switch S1 is open.
F. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74BCT2245DW	ACTIVE	SOIC	DW	20	25	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT2245	Samples
SN74BCT2245NSR	ACTIVE	SO	NS	20	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	0 to 70	BCT2245	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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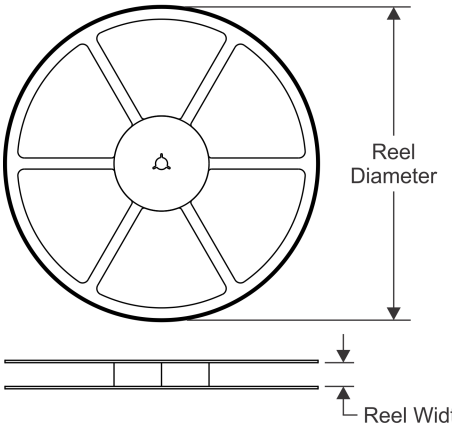
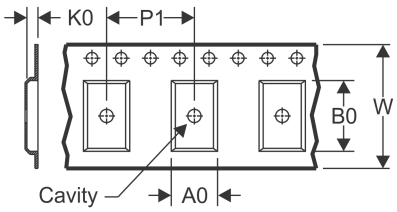
TAPE AND REEL INFORMATION

REEL DIMENSIONS

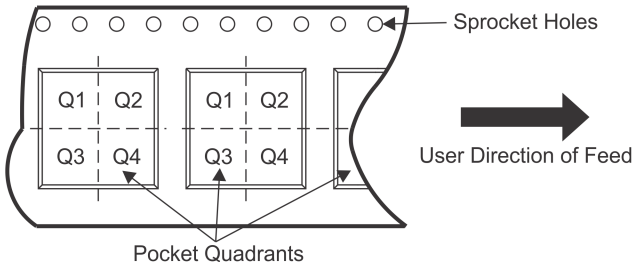


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

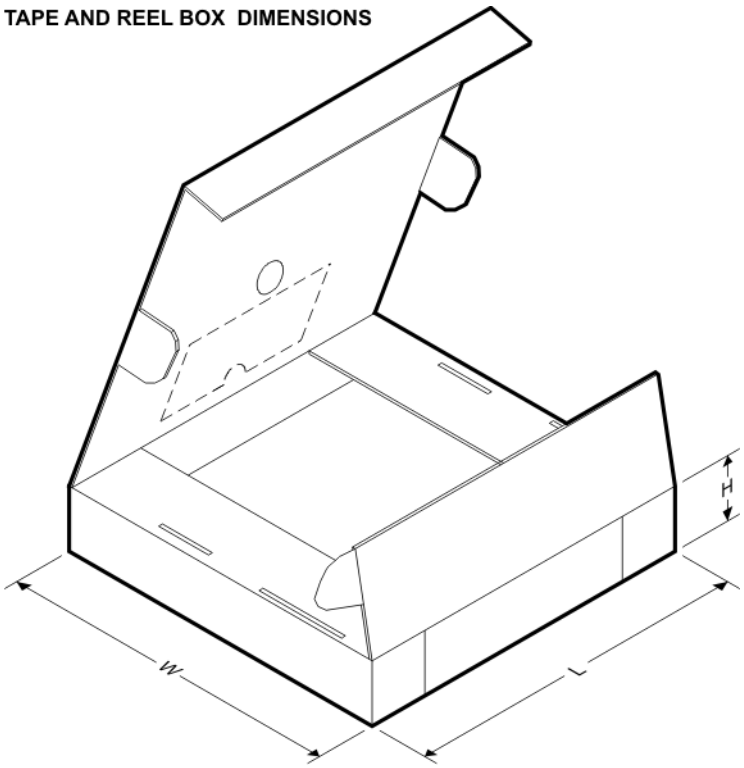
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74BCT2245NSR	SO	NS	20	2000	330.0	24.4	8.4	13.0	2.5	12.0	24.0	Q1

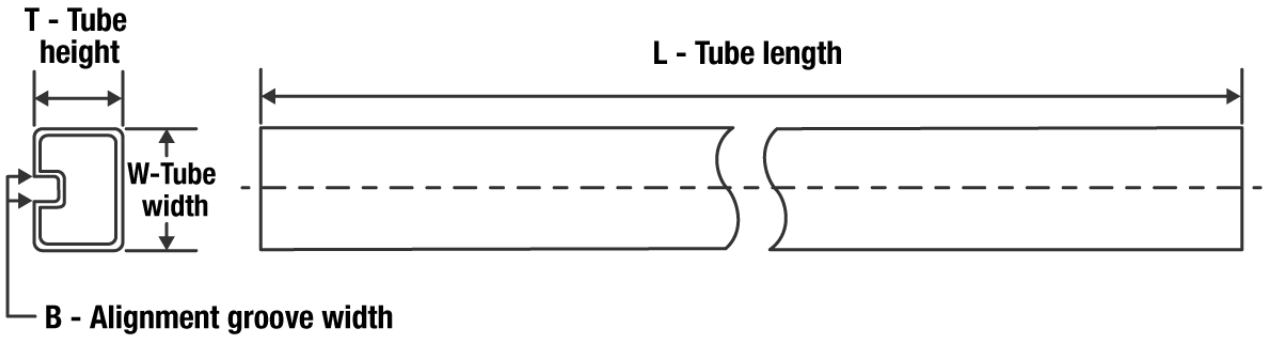
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74BCT2245NSR	SO	NS	20	2000	367.0	367.0	45.0

TUBE



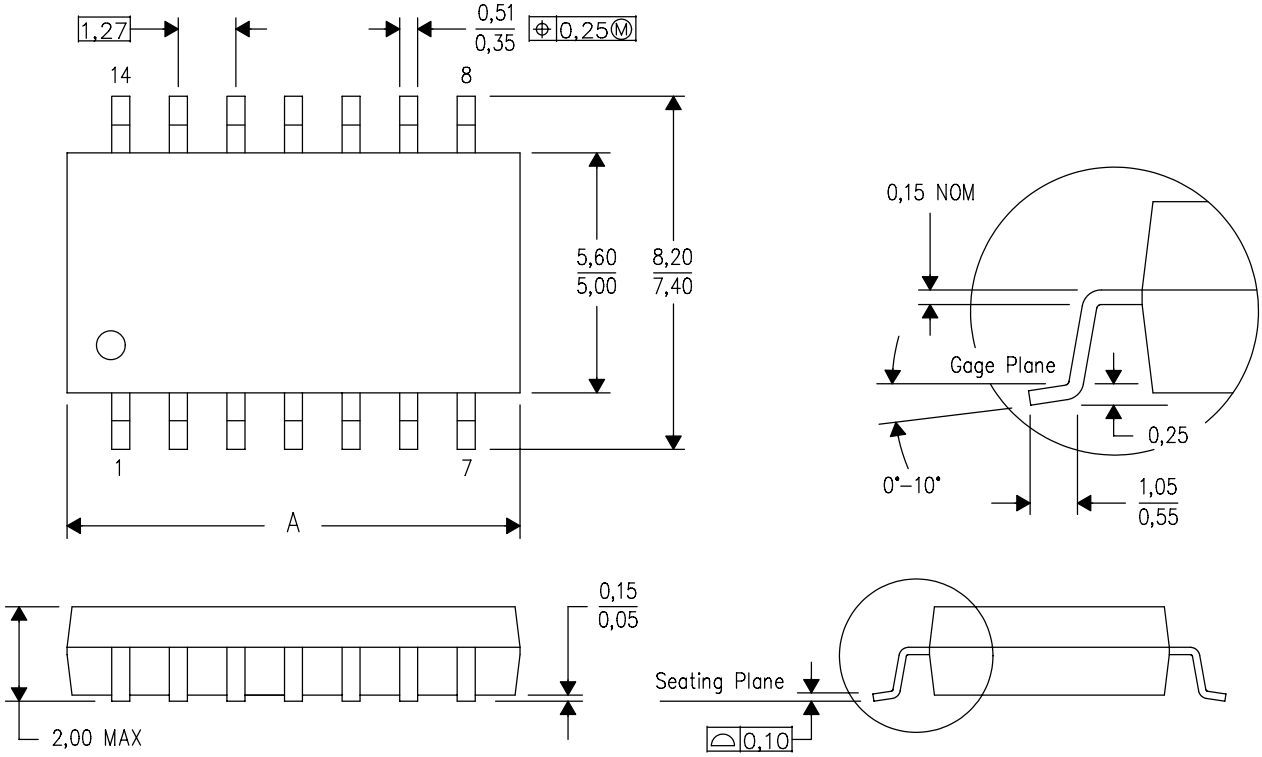
*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74BCT2245DW	DW	SOIC	20	25	507	12.83	5080	6.6

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

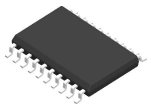
14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

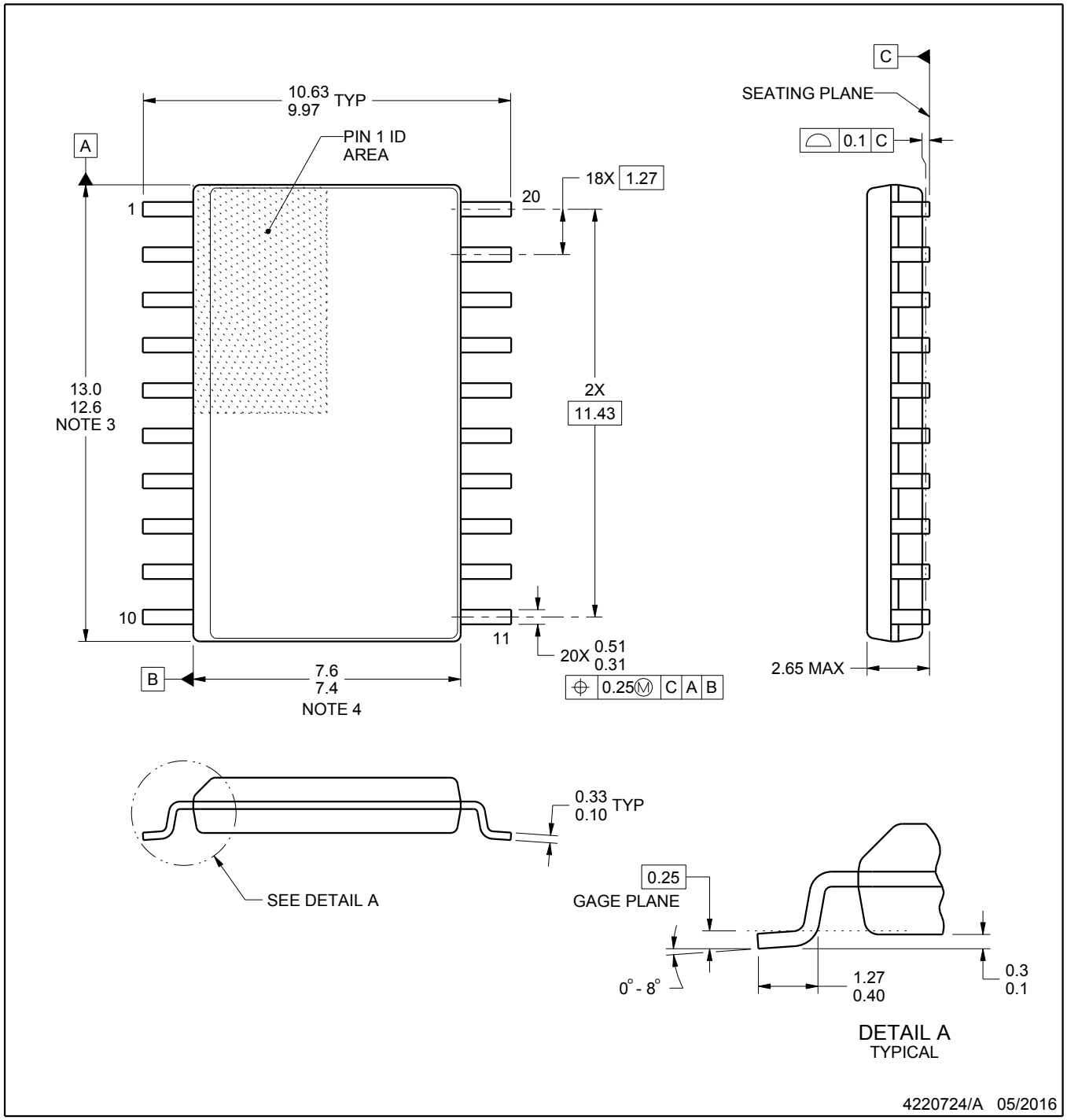


PACKAGE OUTLINE

DW0020A

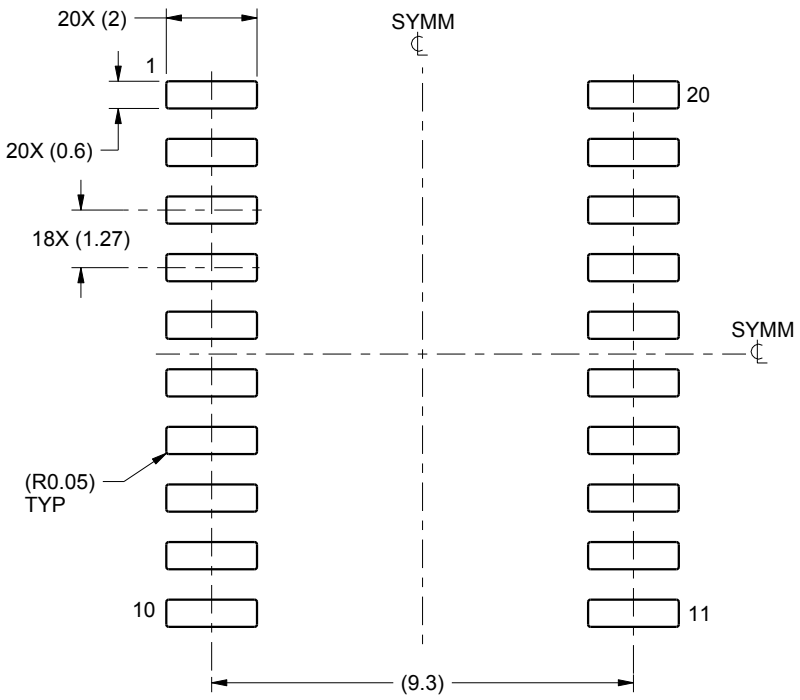
SOIC - 2.65 mm max height

SOIC

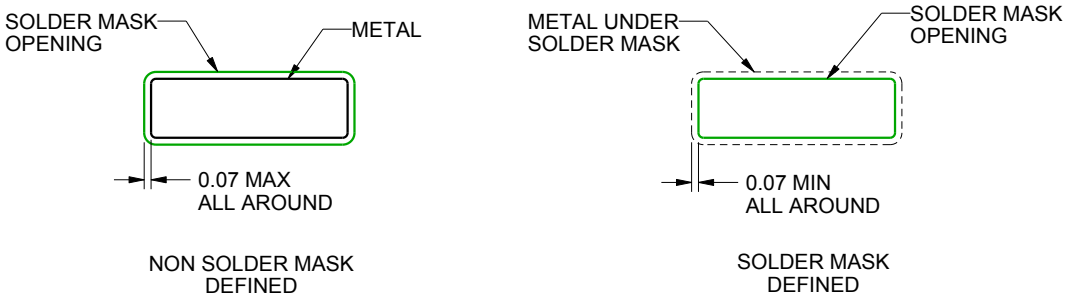


NOTES:

1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
5. Reference JEDEC registration MS-013.



LAND PATTERN EXAMPLE
SCALE:6X

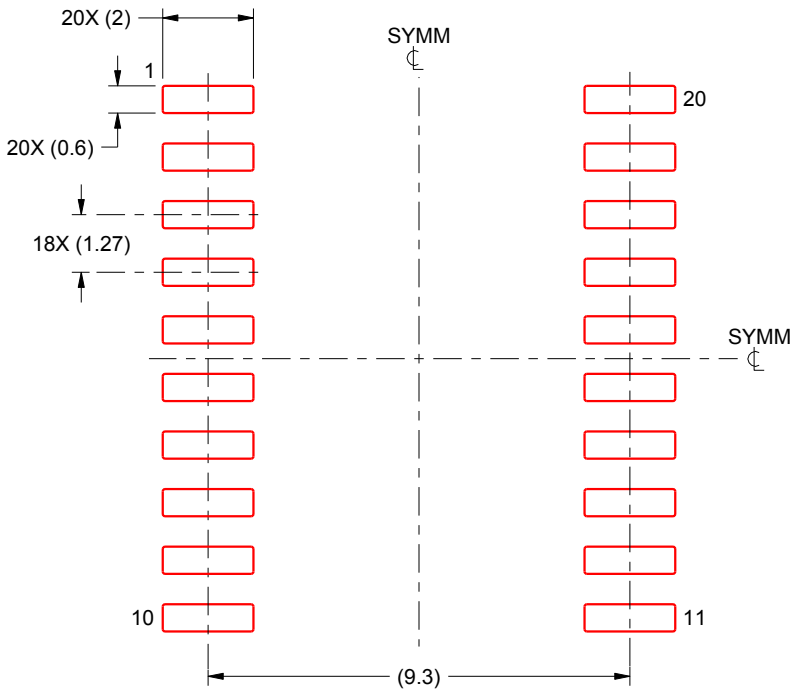


SOLDER MASK DETAILS

4220724/A 05/2016

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:6X

4220724/A 05/2016

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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